# Preparation of Perovskite Bi-Sr-Ca-Cu-O Thin Films by Ion Beam Sputtering : Effects of Oxygen Molecules and Plasma

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Ca-doped and nondoped Bi2201 thin films were grown at low temperatures by ion beam sputtering with supplying oxygen molecule or plasma at various partial pressures ( $P_0$ ). Crystallinity of the Ca-doped films is improved by the plasma only in the low  $P_0$  regions while that of the nondoped films is improved by the molecule in the whole region of  $P_0$ . It is proposed that sputtered particle energy and energy balance are important factors.

Keywords: Bi2201 thin films, Low temperature growth, Oxygen pressure, Oxygen plasma

## 1. INTRODUCTION

High temperature superconductors (HTS) are highly expected to be applied for high frequency devices [1] such as microwave filters [2]. Tunable microwave filters will be widely required as the next generation devices. The tunable filter may be realized by stacking ferromagnetic layers on HTS thin films [3,4]. In such a heterogeneous thin film stacking, surface flatness of the films and prevention of inter-diffusion are essentially important factors. In order to clear these demands, low temperature processing of thin films is most promising [5]. Of course, however, it is very difficult to grow good crystalline thin films at low substrate temperatures due to shortage of thermal energy. Then usually we need some other energies to grow the good crystalline thin films which can compensate the shortage of thermal energy.

Generally it is thought that active oxygen is inevitable for the low temperature growth of perovskite oxide thin films [6]. This must be true for low energy deposition techniques. However, it might not be always necessary for high energy deposition techniques such as PLD and sputterings. From this anticipation we tried to investigate a validity of oxygen plasma for the low temperature growth of Bi2201 thin films employing ion beam sputtering (IBS) since it is easy to control the oxygen supply. Bi2201 has the simplest perovskite structure among various HTS groups. Then it is easier to investigate impurity doping effects on the low temperature growth. It must be noticed that superiorly excellent crystalline Bi2201 thin films can be grown at a higher temperature of 650°C for the Ca-doped system [7,8], and at a 550°C for the nondoped system [9]. However, it is valuable to challenge the lower temperature process yet.

## 2. EXPERIMENTAL

The nondoped Bi2201 (Bi2Sr2CuOx) and Ca-doped Bi2201 (Bi2(Sr,Ca)2CuOx) thin films were deposited on MgO (100) substrate by IBS at low substrate temperatures (T<sub>S</sub>). IBS system is shown in Fig.1 for the sputtering part. Ar gas is introduced into a discharge gap of 1.5 mm between anode (An) and cathode (Ca), and argon plasma (AP) is produced by electrical discharge applying a high voltage (V<sub>a</sub>) of 4 kV on the anode of an ion gun. An and Ca are separated by a ceramic ring (C). Ar<sup>+</sup> ion beam is emitted through a cathode orifice of 1 mm $\Phi$ , and it is collimated by a copper collimator (Co) with  $6mm\Phi$  to focus the Ar<sup>+</sup> ion beam in a target (T) area. The ion beam diameter is 10-15 mm , which is less than a diameter of 20 mm  $\Phi$ of the target. The ion beam flux is monitored by a target current (I<sub>t</sub>), which is ranging from 5 to 10  $\mu$ A/cm<sup>2</sup>.

The target (Bi-Sr-Ca-Cu-O) is sputtered by 4 keV Ar<sup>+</sup> ion beam and sputtered particles (SP) are deposited on the substrate (S). A distance between the ion gun and the target is 30 mm. The substrate is located under the target by 30 mm [10]. During the depositions, oxygen molecule (ML) or plasma (PL) was supplied from a plasma source at various oxygen partial pressures (P<sub>O</sub>). The oxygen plasma was produced in the plasma source by discharging oxygen gas [7-12]. When the oxygen molecules were supplied, the oxygen gas was emitted from the same plasma source without the discharge. The P<sub>O</sub> value was ranged from 0.1 to 6 mTorr for the depositions of nondoped Bi2201 at T<sub>S</sub>=500°C



Fig.1 A schematic diagram of the ion beam sputtering system. See text for notations. A: current meter.

### and Ca-doped Bi2201 at $T_S$ =450°C and 500°C.

The deposited films were characterized by XRD and their crystallinity was estimated by averaged FWHM of (006) and (008) peaks on  $\theta$ -2 $\theta$  scan (Av. $\Delta_{\theta}$ ). The surface morphology of the films was observed by AFM and their roughness was estimated by the average values of  $R_Z$ .

#### 3. RESULTS AND DISCUTTION

XRD patterns are shown in Fig.2 for the 30% Ca-doped Bi2201 thin film deposited at  $T_S = 450^{\circ}C$ with ML at  $P_0 = 1.5$  mTorr, and in Figs.3 and 4 for the 30% Ca-doped Bi2201 thin films deposited at  $T_S =$ 500°C with ML and PL, respectively, at various Po indicated. Attached numbers indicate (001) indices. The XRD of all the films showed c-oriented Bi2201 phase. The XRD pattern of 450°C film (Fig.2) is not good but the main peaks of Bi2201 phase are clearly observed even though T<sub>S</sub> is ultralow. The XRD patterns are excellent for 500°C films (Figs.3 and 4) except for the films with very low and high PO values. Peaks (B') from impurity Bi214 (Bi2SrO4) phase are observed for the ML films at higher PO but they are not observed for the PL films. Then the impurity growth is suppressed by the plasma. Figures 5 and 6 show Av. $\Delta_{\theta}$  vs P<sub>0</sub> for the 30% Ca-doped Bi2201 films deposited with the supply of ML or PL at T<sub>S</sub>=450°C and 500°C, respectively. Figure 7 shows Av. $\Delta_{\theta}$  vs P<sub>0</sub> for the nondoped Bi2201 films deposited at T<sub>S</sub>=500°C. Grossly speaking, they all show that the values of Av. $\Delta_{\theta}$  increase both in the lower and higher P<sub>0</sub> regions for ML and PL. The larger Av. $\Delta_{\theta}$ indicates deterioration of crystallinity which is generally caused by shortage and excess of oxidation power at the low and high  $P_O$  regions, respectively. Av.  $\Delta_{\theta}$  always increases faster with increasing Po in the higher Po regions for PL than for ML. This is caused by the stronger (excess) oxidation power for PL than for ML in such higher Po regions.



Fig.2 XRD pattern of the 30% Ca-doped Bi2201 thin film deposited at 450°C at 1.5 mTorr with ML. M, K : MgO peaks.



Fig.3 XRD patterns of the 30% Ca-doped Bi2201 thin films deposited at 500°C at various  $P_o$  with ML. B': impurity Bi214 phase, A: CuO.

Fig.4 XRD patterns of the 30% Ca-doped Bi2201 thin films deposited at 500°C at various  $P_o$  with PL.



Fig.5. Av. $\Delta_{\theta}$  vs P<sub>0</sub> for the 30% Ca-doped films deposited at T<sub>S</sub>=450°C.

There is the other reason for the deterioration in the higher  $P_0$  regions, that is, collisions between sputtered particles (SP) and the supplied oxygen species [11]. We believe this is more feasible. Kinetic energy of SP is quite important for the low temperature growth, it can enhance surface migration of the deposited particles and formation of the crystal structure compensating shortage of thermal energy. The sputtered particles lose much more energy by this collision in the higher  $P_0$ region, then they cannot assist the surface migration. It results in the deterioration. Collision cross section is larger for PL than for ML due to Coulombic interaction for PL, then SP lose much more energy leading to the higher deterioration for PL at the same  $P_0$ .

#### 3.1 Ca-doped film at 450°C

Though the crystallinity of Ca-doped films deposited at 450°C (Fig. 5) is poor in average due to the shortage of thermal energy, the plasma clearly improves the crystallinity in the lower P<sub>0</sub> region [12]. The best P<sub>0</sub> value is 0.75 mTorr for PL. While, it is improved by ML in the higher P<sub>0</sub> region, and the best P<sub>0</sub> is 1.5 mTorr. The highest quality film with Av. $\Delta_0$ =0.33° is obtained by ML at this T<sub>S</sub>. These results cannot be explained exactly but we believe that energy balance among the ① thermal energy, ② sputtered particle energy after the collision, ③ activated oxygen energy by the collision, and ④ plasma energy, is a critical factor in this system [12].

#### 3.2 Ca-doped film at 500℃

The Ca-doped films deposited at 500°C also show the crystalline improvement by PL at the low  $P_0$ region (Fig.6). This result clearly shows the absolute improvement by PL because the minimum Av. $\Delta_{\theta}$  value is smaller for PL (0.09°) at  $P_0=0.2$  mTorr than for ML (0.12°) at  $P_0=1$  and 1.5 mTorr. The energy balance and the plasma energy must play some role for this improvement. As a whole, the crystallinity is improved



Fig.6. Av. $\Delta_0$  vs P<sub>0</sub> for the 30% Ca-doped films deposited at T<sub>s</sub>=500°C.

at 500°C compared with 450°C owing to the higher thermal energy.

## 3.3 Nondoped film at 500°C

The nondoped films deposited by ML at 500°C (Fig.7) show the better crystallinity (Av. $\Delta_{\theta} = 0.1^{\circ}$  at P<sub>0</sub>=2 and 4 mTorr) than the Ca-doped films (Fig.6) in the same P<sub>0</sub> region. This obviously means that the pure Bi2201 crystal can be grown with the higher crystallinity than the impurity doped Bi2201 crystal. A striking feature for the plasma supply is that there is no improvement effect by PL compared with ML in the whole P<sub>0</sub> region for the nondoped system.

# 3.4 Surface morphology

An example of surface morphology is shown in Fig.8 using SEM photograph for the 30% Ca-doped film deposited at 450°C at 1.5 mTorr by ML. The surface is very smooth when the film is deposited at very low temperature. We evaluated the surface roughness by  $R_Z$  for the Ca-doped films deposited at 500°C. Grossly  $R_Z$  values decrease with increasing  $P_O$ both for ML and PL, indicating that the growth mode



Fig.7. Av. $\Delta_{\theta}$  vs  $P_{0}$  for the nondoped films deposited at  $T_{s}{=}500^{\circ}C.$ 



Fig.8 SEM photograph of the 30% Ca-doped film deposited at 450°C with ML at 1.5 mTorr.

gradually changes from 3D to 2D. This may be due to the optimization of SP energy by the collision. The plasma apparently reduced the surface roughness, then it can enhance multiple nucleation [7].

#### 3.5 Mechanism [7-12]

We believe that Bi2201 grows with Sr-plane on the most surface area during the deposition. A surface energy is higher for the Ca-doped phase than for the nondoped phase since the former has Sr-Ca mixed plane on the surface while the latter has single Sr atom. Then the Ca-doped phase has strain energy and higher entropy energy. The supply of thermal energy and SP energy is sufficient for the nondoped phase with the lower surface energy, then it can be grown well by ML. While, the Ca-doped phase with the higher surface energy needs additional energy, namely, the plasma energy. The plasma energy induces the higher order of Sr-Ca arrangement and the reduction of surface energy, resulting in the higher crystallinity and the smoother surface.

# 4. SUMMARY

The Ca-doped and nondoped Bi2201 thin films were grown at the very low temperatures of  $450^{\circ}$ C and  $500^{\circ}$ C with supplying oxygen molecules or plasma, and the oxygen partial pressure dependence and the oxygen plasma effects were investigated on their crystallinity. For the Ca-doped films the plasma can improve the crystallinity in the low P<sub>O</sub> region, while the

nondoped films are improved by the molecules. We suggest that the collisions between SP and oxygen, and the total energy or energy balance, are the important factors on the low temperature growth. The surface morphology is also improved by the plasma. We proposed the improvement mechanism by the plasma.

## ACKNOWLEDGEMENT

One of the authors S.U. thanks the Ministry of Education and Science of Japan for the award of Monbu-kagakusho fellowship. We thank Dr. Shiomi for XRD measurement, and Dr. Matsui and Dr. Kurosaki for AFM measurement.

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(Received February 5, 2003; Accepted June 30, 2003)